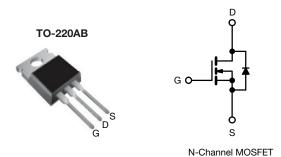


Vishay Siliconix

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMARY				
V_{DS} (V) at T_J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.156		
Q _g max. (nC)	96			
Q _{gs} (nC)	12			
Q _{gd} (nC)	25			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free and halogen-free	SiHP22N60AE-BE3 ^a		
	SiHP22N60AE-GE3		

Note

a. "-BE3" denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	less otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	.,	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	20		
		T _C = 100 °C		12	Α	
Pulsed drain current ^a			I _{DM}	49		
Linear derating factor				1.4	W/°C	
Single pulse avalanche energy b			E _{AS}	204	mJ	
Maximum power dissipation			P_{D}	179	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	$T_{J} = 1$	125 °C	-1) //-14	70	1//	
Reverse diode dV/dt ^d			dV/dt	31	- V/ns	
Soldering recommendations (peak temperature) c	For 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 3.8 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	0.7	C/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS			MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} =	600	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 250 µA		-	0.72	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4	V
0		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I_{GSS}	V _{GS} = ± 30 V		-	-	± 1	μΑ
		V _{DS} =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 \	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A	-	0.156	0.180	Ω
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 11 A		-	4.8	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz			1451	-	pF
Output capacitance	C _{oss}			-	73	-	
Reverse transfer capacitance	C _{rss}			-	5	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V 0V4-400VV 0V		-	50	-	
Effective output capacitance, time related ^b	C _{o(tr)}	V _{DS} = 0 \	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		258	-	
Total gate charge	Qg			-	48	96	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 11 A, V_{DS} = 480 V$	-	12	-	nC
Gate-drain charge	Q _{gd}				25	-	1
Turn-on delay time	t _{d(on)}		$V_{DD} = 480 \text{ V}, I_{D} = 11 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		19	38	ns
Rise time	t _r	V _{DD} =			33	66	
Turn-off delay time	t _{d(off)}				45	90	
Fall time	t _f	1		=.	21	42	
Gate input resistance	R_g	f = 1 MHz, open drain		0.3	0.6	1.2	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	20	
Pulsed diode forward current	I _{SM}			-	-	49	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 11 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	319	638	ns
Reverse recovery charge	Q _{rr}			-	4.9	9.8	μC
Reverse recovery current	I _{RRM}			_	28	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

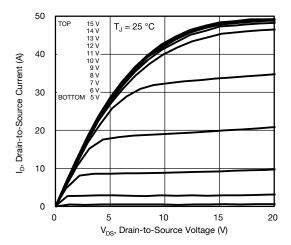


Fig. 1 - Typical Output Characteristics

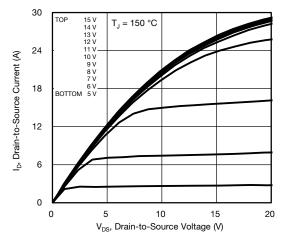


Fig. 2 - Typical Output Characteristics

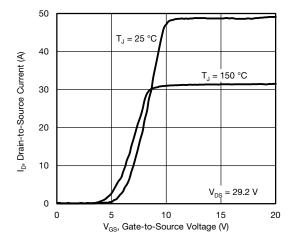


Fig. 3 - Typical Transfer Characteristics

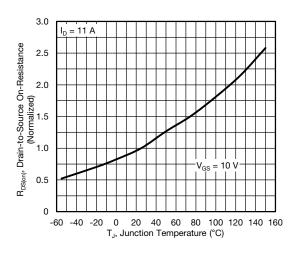


Fig. 4 - Normalized On-Resistance vs. Temperature

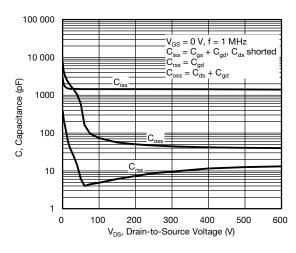


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

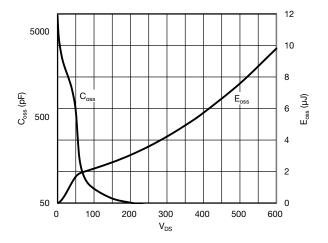


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



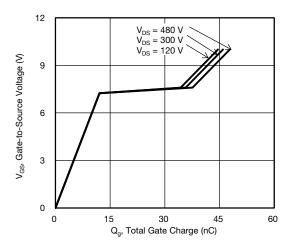


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

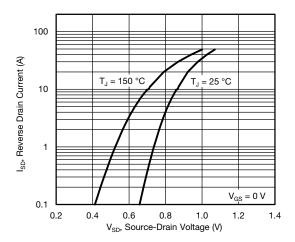


Fig. 8 - Typical Source-Drain Diode Forward Voltage

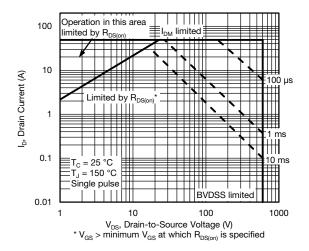


Fig. 9 - Maximum Safe Operating Area

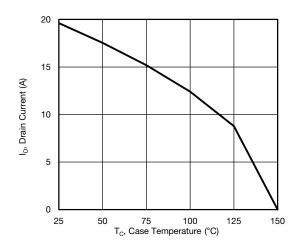


Fig. 10 - Maximum Drain Current vs. Case Temperature

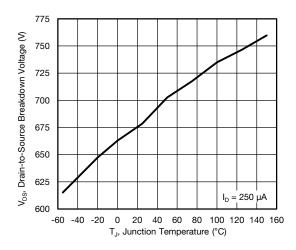


Fig. 11 - Temperature vs. Drain-to-Source Voltage



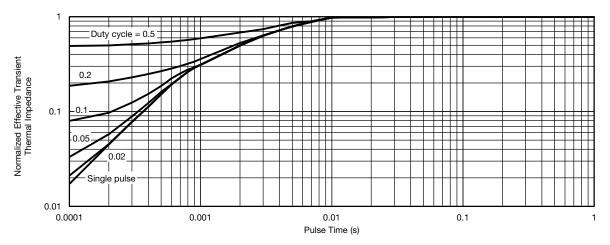


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

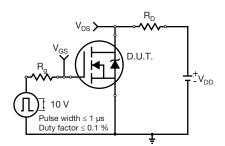


Fig. 13 - Switching Time Test Circuit

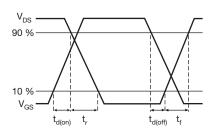


Fig. 14 - Switching Time Waveforms

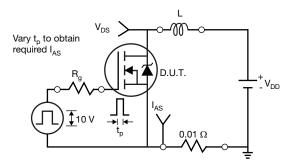


Fig. 15 - Unclamped Inductive Test Circuit

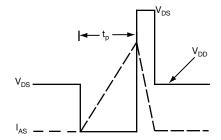


Fig. 16 - Unclamped Inductive Waveforms

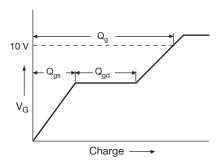


Fig. 17 - Basic Gate Charge Waveform

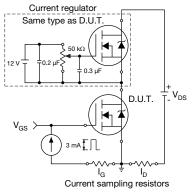
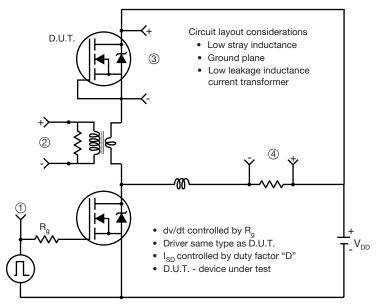


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



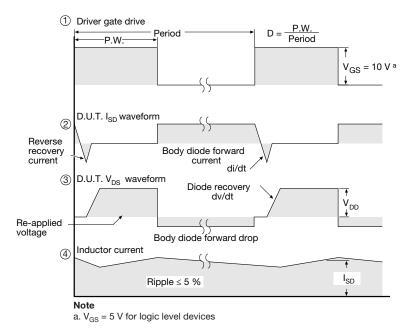


Fig. 19 - For N-Channel

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